

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	372	(first adj polymeric adj material) same (second polymeric adj material)	USPAT	2002/06/05 15:12
2	BRS	L2	17	1 and (bumps or solder)	USPAT	2002/06/05 15:05
3	BRS	L3	46	1 and openings	USPAT	2002/06/05 15:09
4	BRS	L4	0	1 and (flip adj chip)	USPAT	2002/06/05 15:09
5	BRS	L5	0	1 and (flip adj chip)	USPAT; US-PGP UB; EPO; JPO; DERWENT; IBM_TD_B	2002/06/05 15:09
6	BRS	L6	7	microelectronic adj interconnect adj structure	USPAT; US-PGP UB; EPO; JPO; DERWENT; IBM_TD_B	2002/06/05 15:10
7	BRS	L7	0	(polymeric adj material) same (conductive adj bump adj material)	USPAT; US-PGP UB; EPO; JPO; DERWENT; IBM_TD_B	2002/06/05 15:12
8	BRS	L8	9	conductive adj bump adj material	USPAT	2002/06/05 15:13
9	BRS	L9	1051	underfill	USPAT	2002/06/05 15:21
10	BRS	L10	102	9 and (polymeric adj material)	USPAT	2002/06/05 15:58

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8	BRS	L8	9	conductive adj bump adj material	USPAT	2002/06/05 15:13